

AMENDMENTS TO THE CLAIMS

List of Claims:

1. (Currently Amended) A rectification chip terminal structure, mounting a rectification chip into a terminal by soldering and rubber injection and inserting the rectification chip into a pivotal hole on a printed wire board, wherein said terminal comprising:

a rib ring, surrounding the periphery of said terminal;

a platform extended from the middle section of said terminal;

a first buffer groove formed between said platform and said rib ring, and having a groove guiding corner; thereby, when rubber being injected into said terminal, the rubber going through said first buffer groove to constitute a fixing action, and forming a plastic surface to prevent water vapor and air from entering after the rubber being melted and solidified and thus increasing the adhesion between the injected rubber and said terminal; and said platform increases the soldering area of said rectification chip to give a complete solder between said terminal and chip and thus providing the effect for a current of larger ~~power~~ power; and

a second buffer groove formed in a bottom of said terminal in a position corresponding to said first buffer groove.

2. (Currently Amended) The rectification chip terminal structure of claim 1, wherein said terminal is made integrally, and said terminal has a plurality of protruded threads on the surface of the periphery of said terminal to facilitate assembling said terminal into the pivotal hole on a printed wire board, ~~and said first buffer groove has a second buffer groove disposed in said first buffer groove at a position corresponding to the bottom of said terminal.~~

3. (Currently Amended) A rectification chip terminal structure, mounting a rectification chip into a terminal by soldering and rubber injection and inserting the rectification chip into a pivotal hole on a printed wire board, wherein said terminal comprising:

- a rib ring, surrounding the periphery of said terminal;
- a platform extended from the middle section of said terminal;

- a first buffer groove formed between said platform and said rib ring;

- a protruded ring, extended from the periphery of said platform, and said first buffer groove having a groove guiding corner;

thereby, when rubber being injected into said terminal, the rubber going through said first buffer groove to constitute a fixing action, and forming a plastic surface to prevent water vapor and air from entering after the rubber being melted and solidified and thus increasing the adhesion between the injected rubber and said terminal; and said platform increases the soldering area of said rectification chip to give a complete solder between said terminal and chip and thus providing the effect for a current of larger ~~power~~power; and

a second buffer groove formed in a bottom of said terminal in a position corresponding to said first buffer groove.

4. **(New)** The rectification chip terminal structure of claim 1 wherein said second buffer groove provides a buffer deformation stress for the rectification chip when rubber is injected or an external force is exerted, and forms a plastic surface to prevent water vapor and air from entering.

5. **(New)** The rectification chip terminal structure of claim 3 wherein said second buffer groove provides a buffer deformation stress for the rectification chip when rubber is injected or an external force is exerted, and forms a plastic surface to prevent water vapor and air from entering.

6. (New) The rectification chip terminal structure of claim 1, wherein said first buffer groove is located at a position deeper than said platform.

7. (New) The rectification chip terminal structure of claim 3, wherein said first buffer groove is located at a position deeper than said platform.